| ASDCIATION CONNECTING ELECTRONICE INDUSTRIES® International and Par | PC. Bannockl | burn. Illinois. A | ll rights reserved utions. | under both | This docume level parts, t | ent is a declaration er | on of the su | bstances v all lower | within the manufactur level materials for w | rer listed it hich the m | em. Note: | if the item is an as r has engineering | sembly with low responsibility. |
|---|--------------|---|----------------------------|---------------------------------------|-------------------------------|---|-------------------------|-------------------------|--|-----------------------------|-----------|---|---------------------------------|
| | | | | Form Type Distribute | * | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information | | | | | | | |
| upplier Information | | | | | | | | | | | | | |
| Company name* Compa | | | que ID | | Unique ID Authority | | | Response Date* | | | | | |
| nsemi | | | | | | 2024-04-20 | | | | | | | |
| Contact Name Title - Contact | | | et | | 1 | Phone - Contact | ntact* Email - Contact* | | | | | | |
| Product-Env-Stewards Prod | | | duct Enviro Compliance | | | NA | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Representative* Title | | | presentative H | | | Phone - Representative* | | | Email - Representative* | | | | |
| Product-Env-Stewards Produ | | | ro Compliance | iance NA Product-Env-Stewards@onsemi. | | | | m | | | | | |
| Requester Item Number Mfr Item | | n Number Mfr Item Name | | | Effective Date | Version | М | Manufacturing Site | | Weight* | UOM | Unit Type | |
| | | R0220AT4R00XUE 2MP 1/2 CIS SO 1-TRBM | | | | 2024-04-20 | | Т | TWU | | 298.74 | mg | Each |
| Ianufacturing Proccess Informa | tion | | | | | | | | | | | | |
| Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 M | | | | J-STD-020 MSI | Rating | Peak Proce | ss Body Te | emperature | e Max Time at Peak | Temperat | ure Num | ber of Reflow Cyc | les |
| SnAgCu CU Alloy 3 | | | | | | 260 | | С | 30 | secon | ds 3 | | |
| omments | | | | | | | | | | | | | |
| TTENTION: MSL 3 Rated item require | s Bake and I | Dry Pack (after | electrical test) | | | | | | | | | | |
| or more information regarding material | composition | please refer to | page 3 | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | |
|--|--|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | nium (Cr6+), Polybro | ominated Biphenyls (PBB), Polybron | dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth | | | | | | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | ances per the definitio | on above | Supplier Acceptance | * Accepted | | | | | |
| Exemption: If the declared item does not con applicable exemptions. | ntain RoHS restricted substances per | the definition above | except for defined RoHS exempti | ons, then select the corresponding response i | n the RoHS Declaration above and choose all | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | |
| Declaration Signature | | | | | | | | | | |
| Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester. | | | | | | | | | | |
| Supplier Digital Signature Ra | stislav Drska | Le | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|--|------------------|--------|---------|-----------------|
| | 62.85 | mg | | Misc. | proprietary data | | 0.2388 | mg |
| | | | Supplier | Silicon (Si) | 7440-21-3 | | 61.989 | mg |
| | | | Supplier | Aluminum (Al) | 7429-90-5 | | 0.6222 | mg |
| Die Attach | 3.83 | mg | | Bismaleimide Monomer | proprietary data | | 1.4745 | mg |
| | | | Supplier | POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE | 56641-05-5 | | 0.0192 | mg |
| | | | Supplier | 2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate | 55818-57-0 | | 0.383 | mg |
| | | | Supplier | Bis(4-tert-butylcyclohexyl) peroxydicarbonate | 15520-11-3 | | 0.0192 | mg |
| | | | Supplier | 2,2-dimethyl-1,3-propanediyl dimethacrylate | 1985-51-9 | | 0.383 | mg |
| | | | Supplier | 2-phenoxy ethyl acrylate | 48145-04-6 | | 0.383 | mg |
| | | | Supplier | Bisphenol A_Epichlorohydrin Polymer | 25068-38-6 | | 0.0192 | mg |
| | | | Supplier | Other Additive Agents | Proprietary Data | | 0.766 | mg |
| | | | Supplier | Formaldehyde Polymer | 9003-36-5 | | 0.383 | mg |
| Ероху | 1.83 | mg | Supplier | Imidazole Addition | 68490-66-4 | | 0.549 | mg |
| | | | Supplier | Bisphenol A_Epichlorohydrin Polymer | 25068-38-6 | | 0.183 | mg |
| | | | Supplier | Zirconium Dioxide (ZrO2) | 1314-23-4 | | 0.183 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 0.183 | mg |
| | | | Supplier | Formaldehyde Polymer | 9003-36-5 | | 0.732 | mg |
| Imaging Lens | 55.66 | mg | Supplier | Titanium Dioxide (TiO2) | 13463-67-7 | | 2.783 | mg |
| | | | Supplier | Sodium Monoxide (Na2O) | 1313-59-3 | | 2.783 | mg |
| | | | Supplier | Boron Trioxide (B2O3) | 1303-86-2 | | 2.783 | mg |
| | | | Supplier | Zinc Monoxide (ZnO) | 1314-13-2 | | 2.783 | mg |
| | | | В | Antimony Trioxide (Sb2O3) | 1309-64-4 | | 0.2783 | mg |
| | | | Supplier | Aluminum Trioxide (Al2O3) | 1344-28-1 | | 2.783 | mg |
| | | | Supplier | Potassium Monoxide (K2O) | 12136-45-7 | | 2.783 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 38.6837 | mg |
| Mold Compound | 72.64 | mg | | Epoxy resin | proprietary data | | 18.0147 | mg |
| | | | Supplier | Other Additive Agents | Proprietary Data | | 2.3245 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | _ | 7.264 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 42.8576 | mg |

| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | 2.1792 | mg |
|---------------------------|--------|----|----------|---------------------------|------------------|---------|----|
| Passivation | 0.3 | mg | Supplier | Dimethylsilicone | 63148-62-9 | 0.015 | mg |
| | | | Supplier | Organic pigment | Proprietary Data | 0.03 | mg |
| | | | Supplier | Other Epoxy resins | Proprietary Data | 0.255 | mg |
| Solder Ball 49. | 49.42 | mg | Supplier | Silver (Ag) | 7440-22-4 | 1.4826 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | 47.6903 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | 0.2471 | mg |
| Solder Mask 5.6 | 5.605 | mg | | Epoxy resin | proprietary data | 0.6726 | mg |
| | | | Supplier | Acrylate | Proprietary Data | 2.1411 | mg |
| | | | Supplier | Talc | 14807-96-6 | 0.1513 | mg |
| | | | Supplier | Miscellaneous | Trade Secret | 0.2074 | mg |
| | | | Supplier | Barium Sulfate (BaSO4) | 7727-43-7 | 2.4326 | mg |
| Substrate Copper Foil | 4.313 | mg | Supplier | Copper (Cu) | 7440-50-8 | 4.313 | mg |
| Substrate - Core Material | 21.426 | mg | | Epoxy resin | proprietary data | 4.643 | mg |
| | | | Supplier | Fiber Glass (SiO2) | 65997-17-3 | 16.783 | mg |
| Substrate Plating-Au | 0.371 | mg | Supplier | Gold (Au) | 7440-57-5 | 0.371 | mg |
| Substrate Plating-Cu | 19.284 | mg | Supplier | Copper (Cu) | 7440-50-8 | 19.284 | mg |
| Substrate Plating-Ni | 0.891 | mg | В | Nickel (Ni) | 7440-02-0 | 0.891 | mg |
| Wire Bond - Au | 0.32 | mg | Supplier | Gold (Au) | 7440-57-5 | 0.32 | mg |